



**THE DATASHEET OF
2N7002,215**





2N7002

60 V, 300 mA N-channel Trench MOSFET

Rev. 7 — 8 September 2011

Product data sheet

1. Product profile

1.1 General description

N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using Trench MOSFET technology.

1.2 Features and benefits

- Suitable for logic level gate drive sources
- Very fast switching
- Surface-mounted package
- Trench MOSFET technology

1.3 Applications

- Logic level translators
- High-speed line drivers

1.4 Quick reference data

Table 1. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------------------|----------------------------------|---|-----|-----|------|----------|
| V_{DS} | drain-source voltage | $25\text{ °C} \leq T_j \leq 150\text{ °C}$ | - | - | 60 | V |
| I_D | drain current | $V_{GS} = 10\text{ V}$; $T_{sp} = 25\text{ °C}$; see Figure 1 ; see Figure 3 | - | - | 300 | mA |
| P_{tot} | total power dissipation | $T_{sp} = 25\text{ °C}$; see Figure 2 | - | - | 0.83 | W |
| Static characteristics | | | | | | |
| $R_{DS(on)}$ | drain-source on-state resistance | $V_{GS} = 10\text{ V}$; $I_D = 500\text{ mA}$; $T_j = 25\text{ °C}$; see Figure 6 ; see Figure 8 | - | 2.8 | 5 | Ω |

2. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-------------|----------------------|----------------|
| 1 | G | gate | SOT23 (TO-236AB) | mbb076 |
| 2 | S | source | | |
| 3 | D | drain | | |

3. Ordering information

Table 3. Ordering information

| Type number | Package | | Version |
|-------------|----------|--|---------|
| | Name | Description | |
| 2N7002 | TO-236AB | plastic surface-mounted package; 3 leads | SOT23 |

4. Marking

Table 4. Marking codes

| Type number | Marking code ^[1] |
|-------------|-----------------------------|
| 2N7002 | 12% |

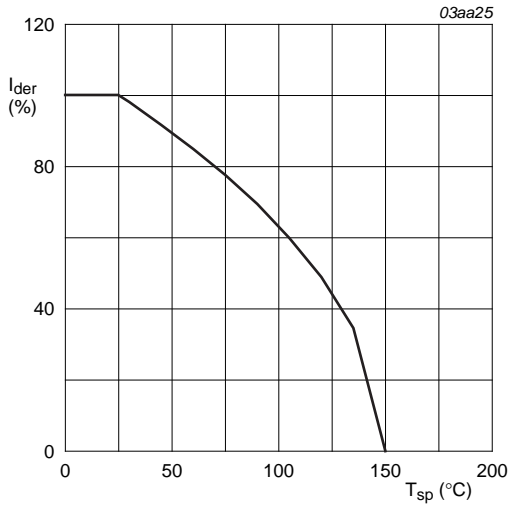
[1] % = placeholder for manufacturing site code

5. Limiting values

Table 5. Limiting values

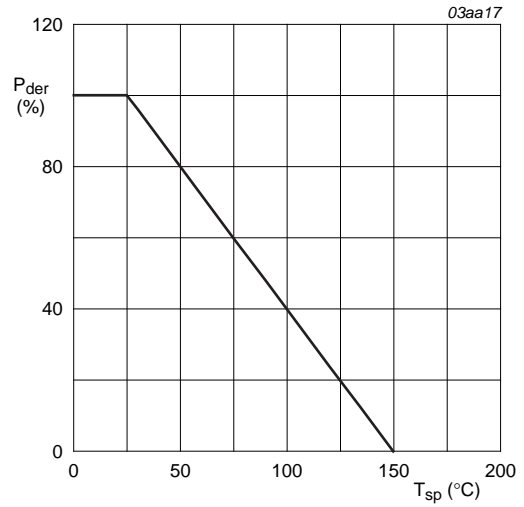
In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|---------------------------|--------------------------|---|-----|------|------|
| V_{DS} | drain-source voltage | $25\text{ °C} \leq T_j \leq 150\text{ °C}$ | - | 60 | V |
| V_{DGR} | drain-gate voltage | $25\text{ °C} \leq T_j \leq 150\text{ °C}$; $R_{GS} = 20\text{ k}\Omega$ | - | 60 | V |
| V_{GS} | gate-source voltage | | -30 | 30 | V |
| V_{GSM} | peak gate-source voltage | pulsed; $t_p \leq 50\text{ }\mu\text{s}$; $\delta = 0.25$ | -40 | 40 | V |
| I_D | drain current | $V_{GS} = 10\text{ V}$; $T_{sp} = 25\text{ °C}$; see Figure 1 ; see Figure 3 | - | 300 | mA |
| | | $V_{GS} = 10\text{ V}$; $T_{sp} = 100\text{ °C}$; see Figure 1 | - | 190 | mA |
| I_{DM} | peak drain current | pulsed; $t_p \leq 10\text{ }\mu\text{s}$; $T_{sp} = 25\text{ °C}$; see Figure 3 | - | 1.2 | A |
| P_{tot} | total power dissipation | $T_{sp} = 25\text{ °C}$; see Figure 2 | - | 0.83 | W |
| T_j | junction temperature | | -65 | 150 | °C |
| T_{stg} | storage temperature | | -65 | 150 | °C |
| Source-drain diode | | | | | |
| I_S | source current | $T_{sp} = 25\text{ °C}$ | - | 300 | mA |
| I_{SM} | peak source current | pulsed; $t_p \leq 10\text{ }\mu\text{s}$; $T_{sp} = 25\text{ °C}$ | - | 1.2 | A |



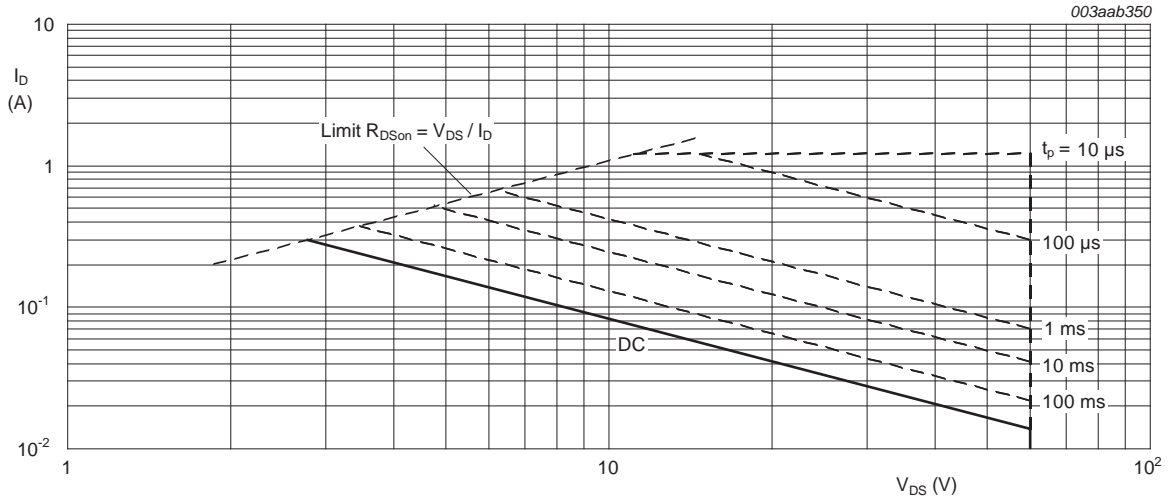
$$I_{der} = \frac{I_D}{I_{D(25^\circ\text{C})}} \times 100\%$$

Fig 1. Normalized continuous drain current as a function of solder point temperature



$$P_{der} = \frac{P_{tot}}{P_{tot(25^\circ\text{C})}} \times 100\%$$

Fig 2. Normalized total power dissipation as a function of solder point temperature



$T_{sp} = 25^\circ\text{C}; I_{DM}$ is single pulse

Fig 3. Safe operating area; continous and peak drain currents as a function of drain-source voltage

6. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------------|--|---|-----|-----|-----|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | Mounted on a printed-circuit board; minimum footprint ; vertical in still air | - | - | 350 | K/W |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point | see Figure 4 | - | - | 150 | K/W |

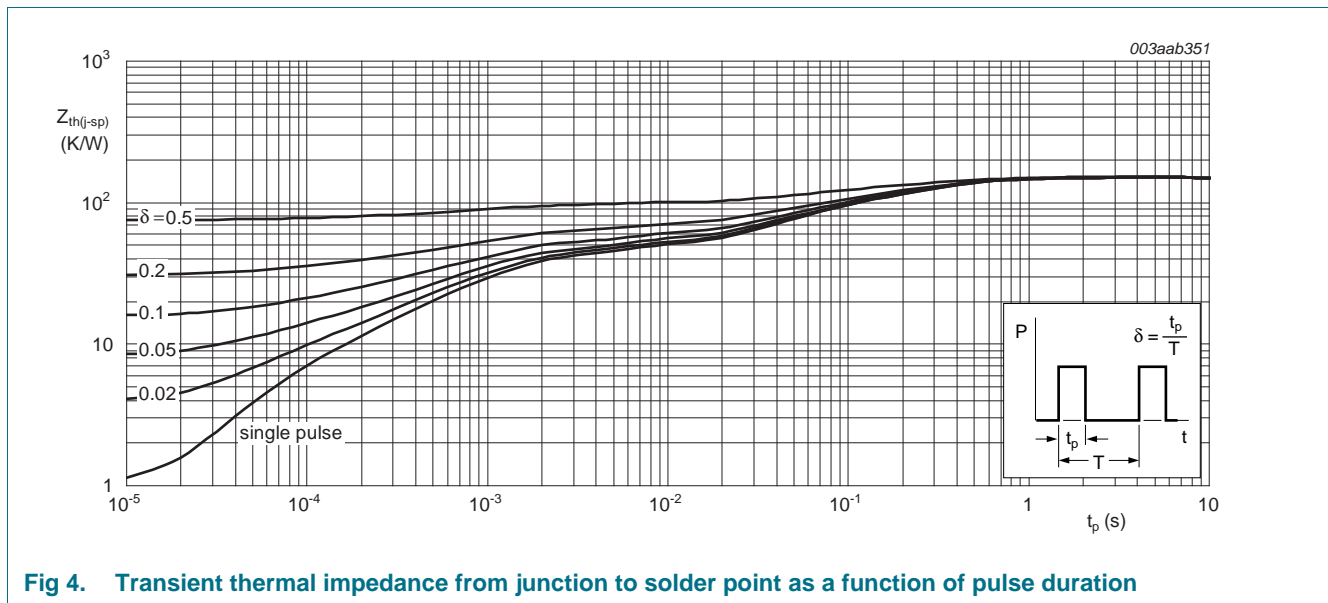


Fig 4. Transient thermal impedance from junction to solder point as a function of pulse duration

7. Characteristics

Table 7. Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------------------|----------------------------------|---|-----|------|------|---------------|
| Static characteristics | | | | | | |
| $V_{(BR)DSS}$ | drain-source breakdown voltage | $I_D = 10 \mu\text{A}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | 60 | - | - | V |
| | | $I_D = 10 \mu\text{A}; V_{GS} = 0 \text{ V}; T_j = -55 \text{ }^\circ\text{C}$ | 55 | - | - | V |
| V_{GSth} | gate-source threshold voltage | $I_D = 0.25 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ }^\circ\text{C};$ see Figure 9 ; see Figure 10 | 1 | 2 | 2.5 | V |
| | | $I_D = 0.25 \text{ mA}; V_{DS} = V_{GS}; T_j = 150 \text{ }^\circ\text{C};$ see Figure 9 ; see Figure 10 | 0.6 | - | - | V |
| | | $I_D = 0.25 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ }^\circ\text{C};$ see Figure 9 ; see Figure 10 | - | - | 2.75 | V |
| I_{DSS} | drain leakage current | $V_{DS} = 48 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | - | 0.01 | 1 | μA |
| | | $V_{DS} = 48 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 150 \text{ }^\circ\text{C}$ | - | - | 10 | μA |
| I_{GSS} | gate leakage current | $V_{GS} = 15 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | - | 10 | 100 | nA |
| | | $V_{GS} = -15 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | - | 10 | 100 | nA |
| R_{DSon} | drain-source on-state resistance | $V_{GS} = 10 \text{ V}; I_D = 500 \text{ mA}; T_j = 25 \text{ }^\circ\text{C};$ see Figure 6 ; see Figure 8 | - | 2.8 | 5 | Ω |
| | | $V_{GS} = 10 \text{ V}; I_D = 500 \text{ mA}; T_j = 150 \text{ }^\circ\text{C};$ see Figure 6 ; see Figure 8 | - | - | 9.25 | Ω |
| | | $V_{GS} = 4.5 \text{ V}; I_D = 75 \text{ mA}; T_j = 25 \text{ }^\circ\text{C};$ see Figure 6 ; see Figure 8 | - | 3.8 | 5.3 | Ω |
| Dynamic characteristics | | | | | | |
| C_{iss} | input capacitance | $V_{DS} = 10 \text{ V}; f = 1 \text{ MHz}; V_{GS} = 0 \text{ V};$ $T_j = 25 \text{ }^\circ\text{C}$ | - | 31 | 50 | pF |
| C_{oss} | output capacitance | | - | 6.8 | 30 | pF |
| C_{rss} | reverse transfer capacitance | | - | 3.5 | 10 | pF |
| t_{on} | turn-on time | $V_{GS} = 10 \text{ V}; V_{DS} = 50 \text{ V}; R_L = 250 \text{ } \Omega;$ $R_{G(ext)} = 50 \text{ } \Omega; R_{GS} = 50 \text{ } \Omega$ | - | 2.5 | 10 | ns |
| t_{off} | turn-off time | | - | 11 | 15 | ns |
| Source-drain diode | | | | | | |
| V_{SD} | source-drain voltage | $I_S = 300 \text{ mA}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C};$ see Figure 11 | - | 0.85 | 1.5 | V |
| Q_r | recovered charge | $V_{GS} = 0 \text{ V}; I_S = 300 \text{ mA};$ $di_S/dt = -100 \text{ A}/\mu\text{s}$ | - | 30 | - | nC |
| t_{rr} | reverse recovery time | | - | 30 | - | ns |

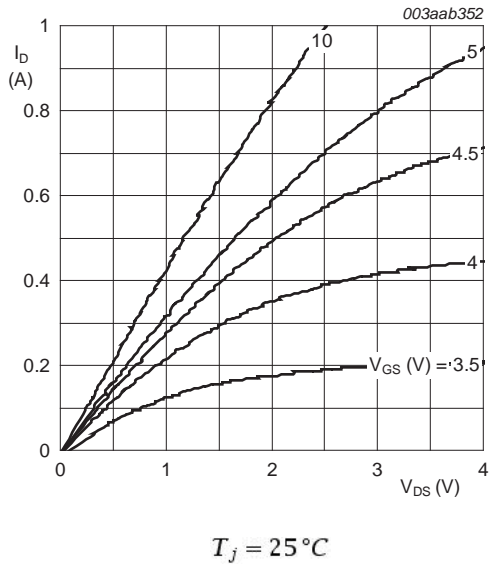


Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values

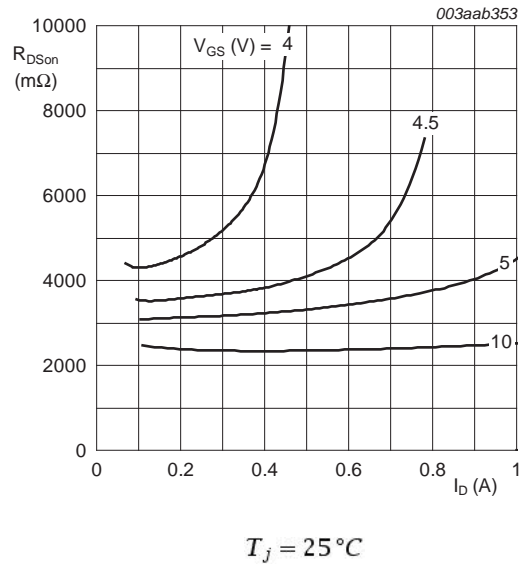


Fig 6. Drain-source on-state resistance as a function of drain current; typical values

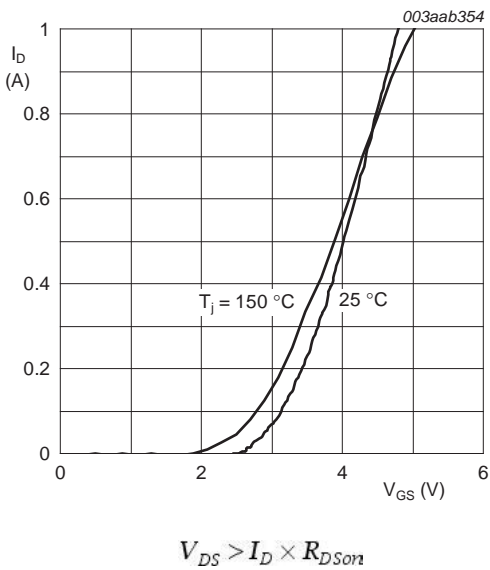


Fig 7. Transfer characteristics: drain current as a function of gate-source voltage; typical values

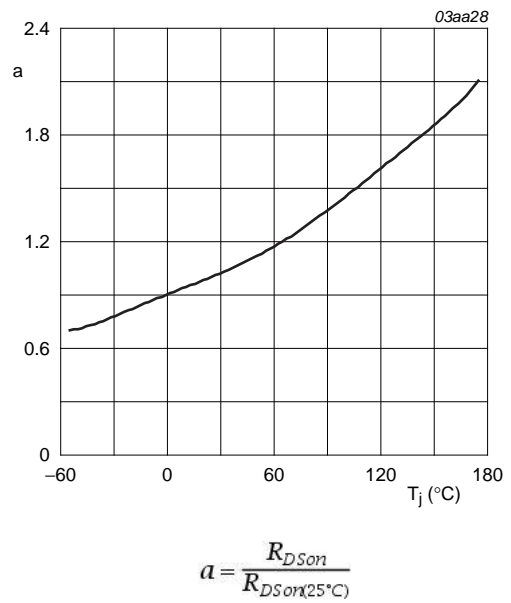


Fig 8. Normalized drain-source on-state resistance factor as a function of junction temperature

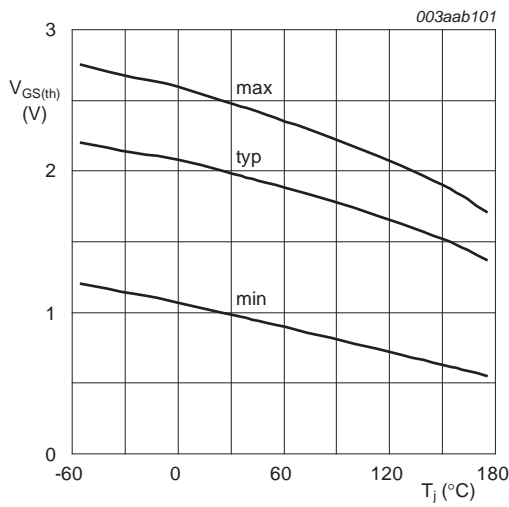


Fig 9. Gate-source threshold voltage as a function of junction temperature

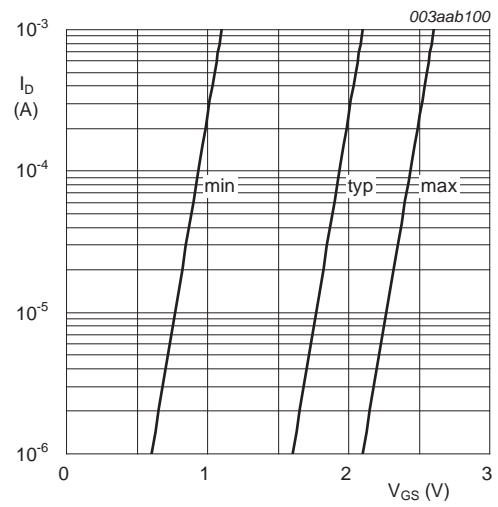


Fig 10. Sub-threshold drain current as a function of gate-source voltage

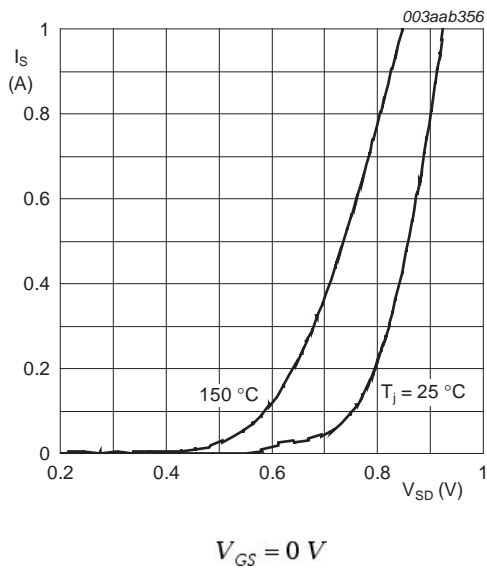


Fig 11. Source current as a function of source-drain voltage; typical values

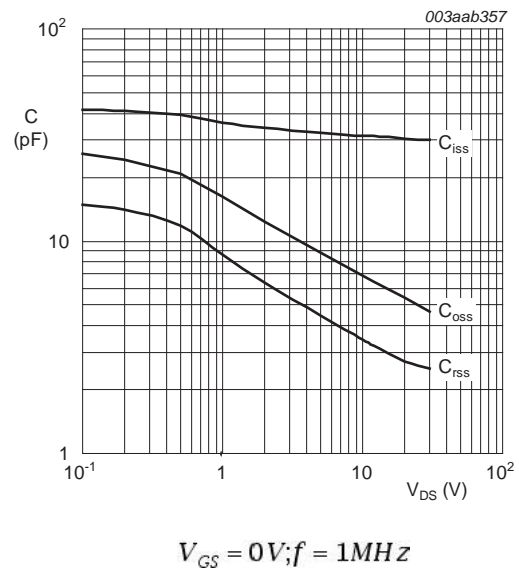


Fig 12. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

8. Package outline

Plastic surface-mounted package; 3 leads

SOT23

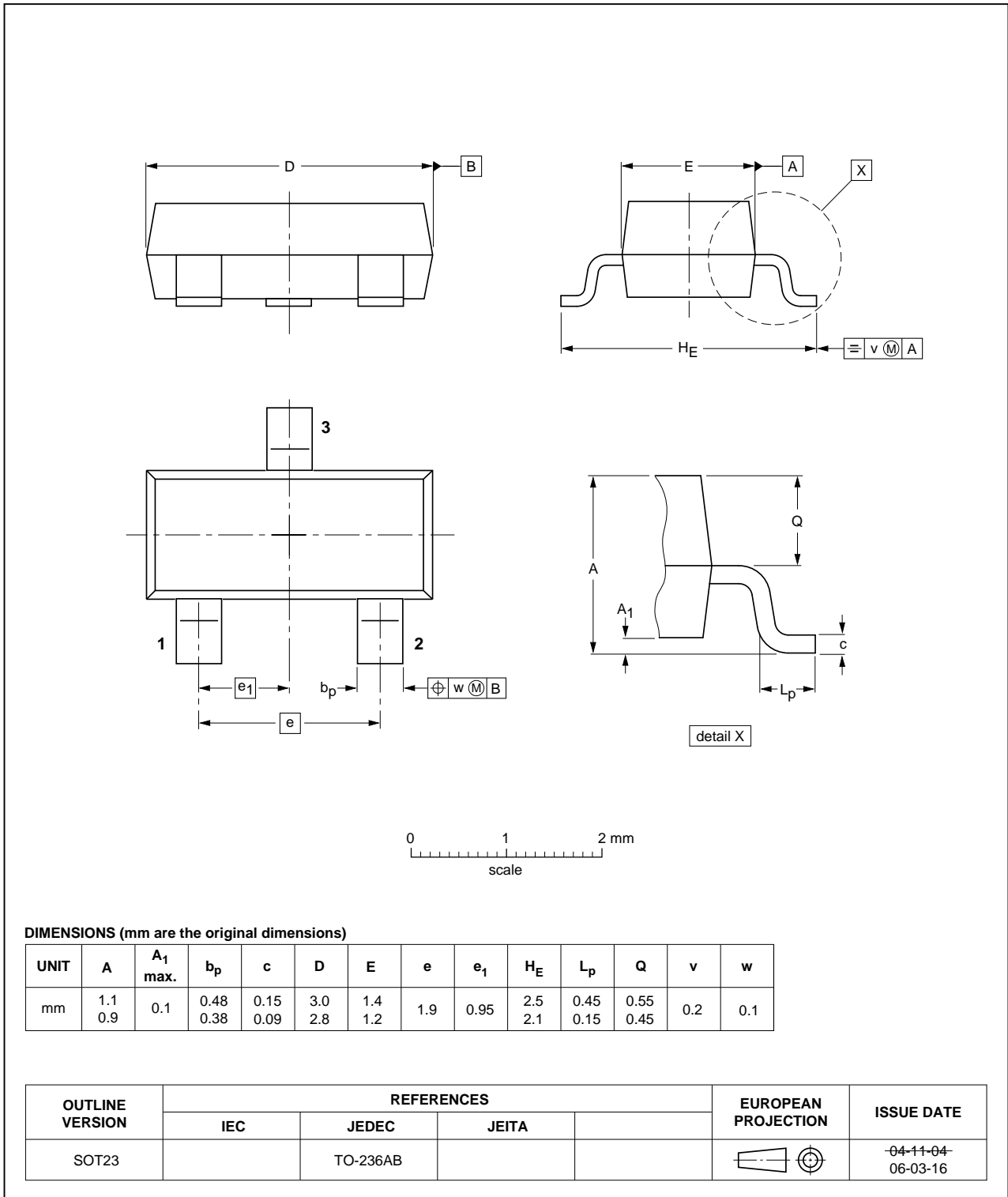


Fig 13. Package outline SOT23 (TO-236AB)

9. Soldering

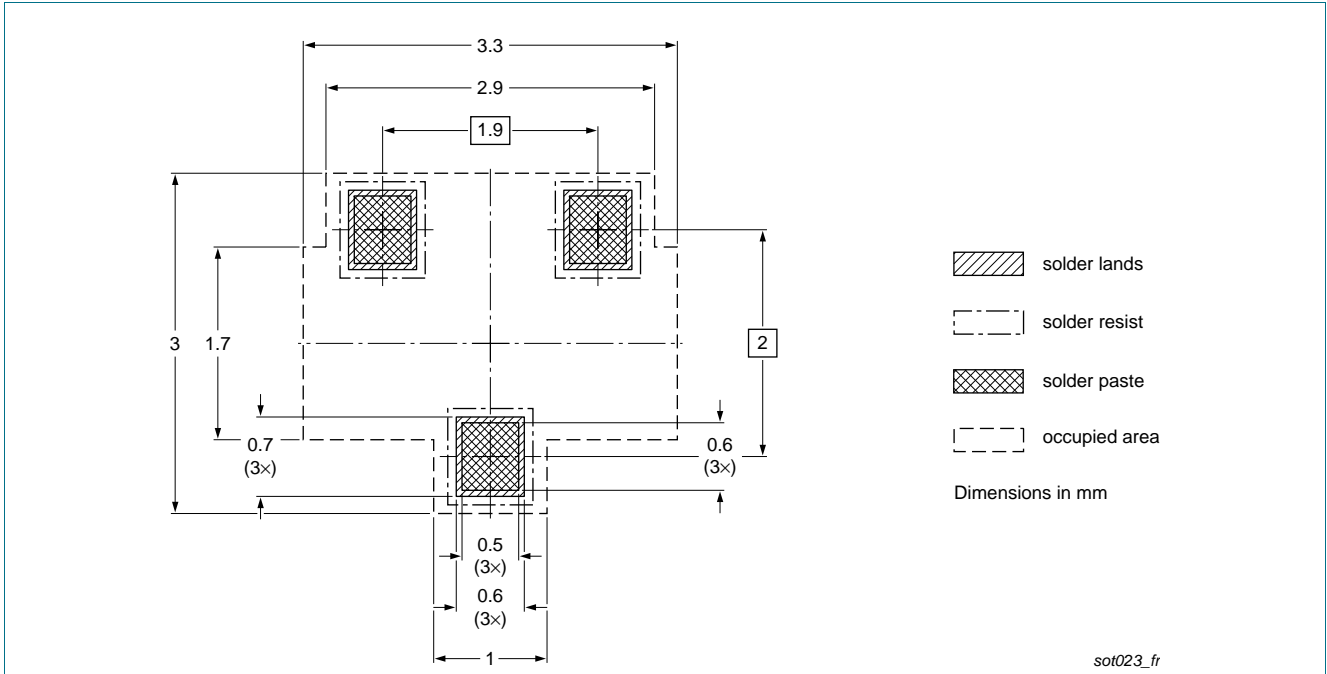


Fig 14. Reflow soldering footprint for SOT23 (TO-236AB)

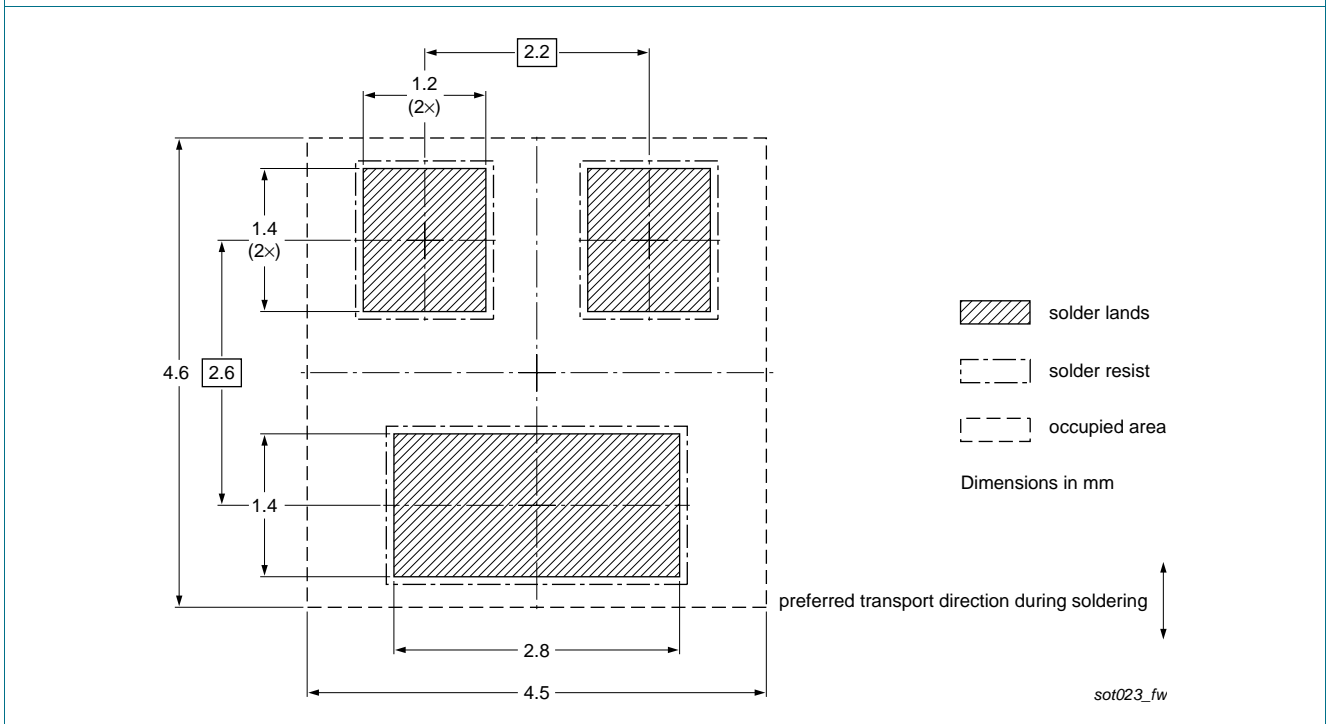


Fig 15. Wave soldering footprint for SOT23 (TO-236AB)

10. Revision history

Table 8. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|----------------|--|-----------------------|---------------|------------|
| 2N7002 v.7 | 20110908 | Product data sheet | - | 2N7002 v.6 |
| Modifications: | <ul style="list-style-type: none">• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.• Legal texts have been adapted to the new company name where appropriate. | | | |
| 2N7002 v.6 | 20060428 | Product data sheet | | 2N7002 v.5 |
| 2N7002 v.5 | 20051115 | Product data sheet | | 2N7002 v.4 |
| 2N7002 v.4 | 20050426 | Product data sheet | | 2N7002 v.3 |
| 2N7002 v.3 | 20000727 | Product specification | HZG336 | 2N7002 v.2 |
| 2N7002 v.2 | 19970617 | Product specification | | 2N7002 v.1 |
| 2N7002 v.1 | 19901031 | Product specification | - | - |

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|---|-------------------------------|---|
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| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

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